

LISTING OF CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

5. (Currently Amended) An inductor comprising:
- a substrate comprising a semiconductor material;
  - a first dielectric layer over the substrate;
  - a first magnetic layer over the first dielectric layer to reduce eddy currents;
  - a second dielectric layer over the magnetic layer; ~~and~~
  - a conductor over the second dielectric layer;
  - a second magnetic layer over the conductor; and
- wherein the magnetic layer comprises an amorphous alloy comprising cobalt, zirconium, and at least one element selected from the list of tantalum, niobium, and a rare earth element.
6. (Currently Amended) An inductor comprising:
- a substrate comprising a semiconductor material;
  - a first dielectric layer over the substrate;
  - a magnetic layer over the first dielectric layer;
  - a second dielectric layer over the magnetic layer; and
  - a conductor over the second dielectric layer;

wherein the magnetic layer defines at least one slot independent of a shape of the conductor.


7. (Currently Amended) An inductor comprising:  
a substrate comprising a semiconductor material;  
a first dielectric layer over the substrate;  
a first magnetic layer over the first dielectric layer to reduce eddy currents;

a second dielectric layer over the magnetic layer;  
a conductor over the second dielectric layer;  
a third dielectric layer over the conductor; and  
~~another~~ a second magnetic layer over the third dielectric layer.

8. (Original) The inductor of claim 7, wherein the other magnetic layer defines at least one slot.

9. (Original) The inductor of claim 7, wherein the magnetic layers are connected.

11. (withdrawn from consideration) The inductor of claim 1, wherein the first dielectric layer and the magnetic layer define one or more trenches and wherein the conductor defines a signal path along the one or more trenches.

 18. (withdrawn from consideration) The inductor of claim 12, wherein the first dielectric layer defines one or more trenches and wherein the conductor defines a signal path along the one or more trenches.

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